

bq2415x YFF EVM

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1 Introduction

1.1 EVM Features

- Evaluation Module For BQ2415x
- High Efficiency Fully Integrated NMOS-NMOS Synchronous Buck Charger With 3MHz Frequency
- Integrated Power FETs for Up To 1.25-A Charge Rate
- Programmable Battery Voltage, Charge Current, and Input Current via I²C Interface
- Input Operating Range 4 V–6 V
- Boost Mode Operation for USB OTG
- LED Indication for Status Signals
- Test Points for Key Signals Available for Testing Purpose. Easy Probe Hook-up
- Jumpers Available. Easy to Change Connections.

1.2 General Description

The bq2415x evaluation module is a complete charger module for evaluating compact, flexible, high-efficiency, USB-friendly switch-mode charge management solution for single-cell Li-ion and Li-polymer batteries used in a wide range of portable applications.

The bq2415x integrates a synchronous PWM controller, power MOSFETs, input current sensing, high-accuracy current and voltage regulation, and charge termination, into a small WCSP package.

The charge parameters can be programmed through an I²C interface.

For details, see the bq2415x data sheets ([SLUS824](#) and [SLUS847](#)).

1.3 I/O Description

Jack	Description
J1-DC+	AC adapter or USB, positive output
J1-DC-	AC adapter or USB, negative output
J2-BAT-	Battery negative terminal, connect to DC-
J2-BAT+	Connect to AUXPWR pin, connect to battery positive terminal
J2-CSOUT	Charger positive output, connect to CSOUT pin
J3-SCL	I ² C clock, connect to SCL pin
J3-SDA	I ² C data, connect to SDA pin
J3-DC-	AC adapter or USB, negative output
J4-STAT	Status output, can be connected to STAT pin by JMP1 set to EXT (2-3)
J4-OTG	Connect to OTG pin
J4-DC-	AC adapter or USB, negative output

1.4 Control and Key Parameters Setting

Jack	Description	Factory Setting
JMP1	LED 1-2: Connect STAT pin to LED on EVM EXT 2-3: Connect STAT pin to J4-1	Jumper On LED (1-2)
JMP2	HI 1-2: OTG high (input or battery voltage) LO 2-3: OTG low (ground)	Jumper On LO (2-3)
JMP3	J2-BAT+ connect to J2-CSOUT	Jumper On

1.5 Recommended Operating Conditions

		Min	Typ	Max	Unit	Notes
Supply voltage, V _{IN}	Input voltage from ac adapter input	4	5	6	V	
Battery voltage, V _{BAT}	Voltage applied at VBAT terminal of J8	0	3-4.2	4.44	V	
Supply current, I _{AC}	Maximum input current from ac adapter input	0	0.1-0.5	1.5	A	
Charge current, I _{chrg}	Battery charge current	0.55	0.7	1.25	A	
Operating junction temperature range, T _J		0		125	°C	

2 Test Summary

2.1 Definitions

This procedure details how to configure the HPA256 evaluation board. On the test procedure the following naming conventions are followed. Refer to the HPA256 schematic for details.

VXXX :	External voltage supply name (VADP, VBT, VSBT)
LOADW:	External load name (LOADR, LOADI)
V(TPyyy):	Voltage at internal test point TPyyy. For example, V(TP12) means the voltage at TP12.
V(Jxx):	Voltage at jack terminal Jxx
V(TP(XXX)):	Voltage at test point "XXX". For example, V(ACDET) means the voltage at the test point which is marked as "ACDET".
V(XXX, YYY):	Voltage across point XXX and YYY.
I(JXX(YYY)):	Current going out from the YYY terminal of jack XX.
Jxx(BBB):	Terminal or pin BBB of jack xx
Jxx ON :	Internal jumper Jxx terminals are shorted
Jxx OFF:	Internal jumper Jxx terminals are open
Jxx (-YY-)	ON: Internal jumper Jxx adjacent terminals marked as "YY" are shorted
Measure: → A,B	Check specified parameters A, B. If measured values are not within specified limits the unit under test has failed.
Observe → A,B	Observe if A, B occur. If they do not occur, the unit under test has failed.

Assembly drawings have location for jumpers, test points and individual components.

2.2 Equipment

2.2.1 POWER SUPPLIES

Power Supply #1 (PS#1): a power supply capable of supplying 5-V at 2-A is required.

2.2.2 LOAD #1

A 10V (or above), 2A (or above) electronic load that can operate at constant current mode.

2.2.3 LOAD #2

A HP 6060B 3-60V/0–60A, 300W system DC electronic load.
Or: equivalent

2.2.4 METERS

Four Fluke 75, (equivalent or better)
Or: Two equivalent voltage meters and two equivalent current meters. The current meters must be able to measure 2A current.

2.2.5 COMPUTER

A computer with at least one USB port and a USB cable. The bq2415x evaluation software must be properly installed.

2.2.6 HPA172 COMMUNICATION KIT

A HPA172 USB to I2C communication kit.

2.2.7 SOFTWARE

Double click on the "SETUP.EXE" file. Follow the installation steps.

2.3 Equipment Setup

- Set the power supply #1 for $5V \pm 100mV$ DC, $2.0 \pm 0.1A$ current limit and then turn off supply.
- Connect the output of power supply #1 in series with a current meter (multimeter) to J1 (DC+, DC-).
- Connect a voltage meter across J1 (DC+, DC-).
- Connect the Load #2 in series with a current meter (multimeter) to J2 (CSOUT, BAT-). Make sure a voltage meter is connected across J2 (BAT+, BAT-). Turn on the Load #2. Use the constant voltage mode. Set the output voltage to 2.5V.
- Turn off Load #2.
- Connect J5 to HPA172 kit by 10-pin ribbon cable. Connect the USB port of the HPA172 kit to the USB port of the computer. The connections are shown in [Figure 1](#).

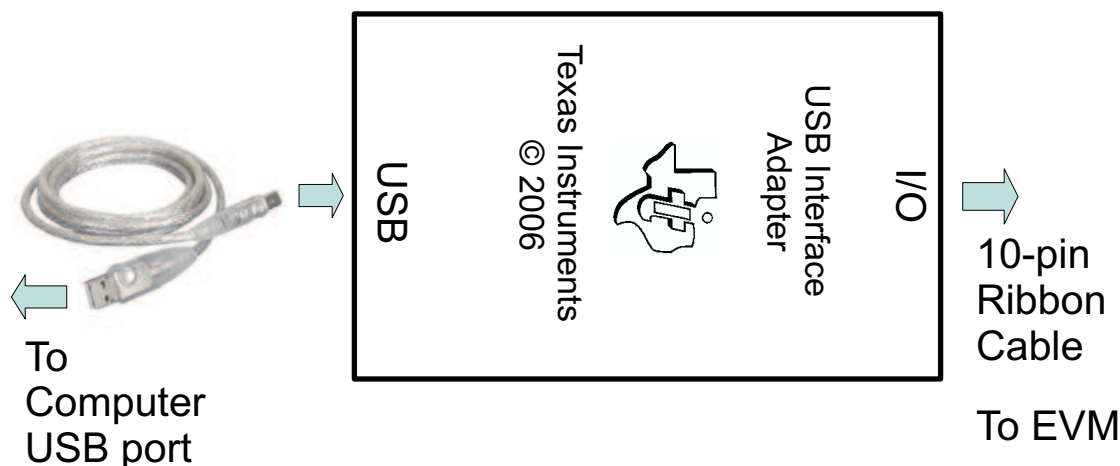


Figure 1. Connections of the HPA172 Kit

- Installed jumpers JMP1(-LED-): ON, JMP2(-LO-): ON, JMP3: ON.
- After the steps above, the test setup for HPA272 is shown in [Figure 2](#)

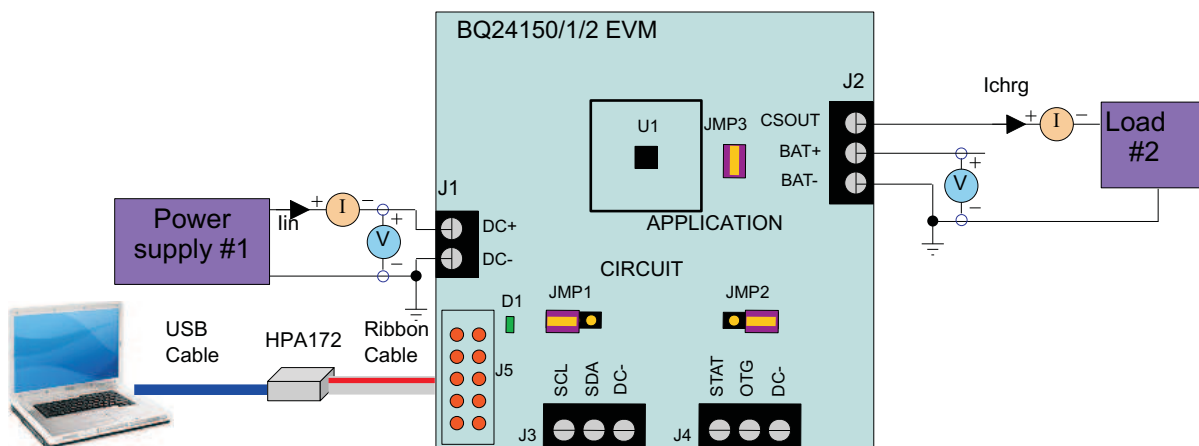


Figure 2. Original Test Setup for HPA256 (bq2415x EVM)

1. Turn on the computer. Open the bq2415x evaluation software. The main window of the software is shown in Figure 3.

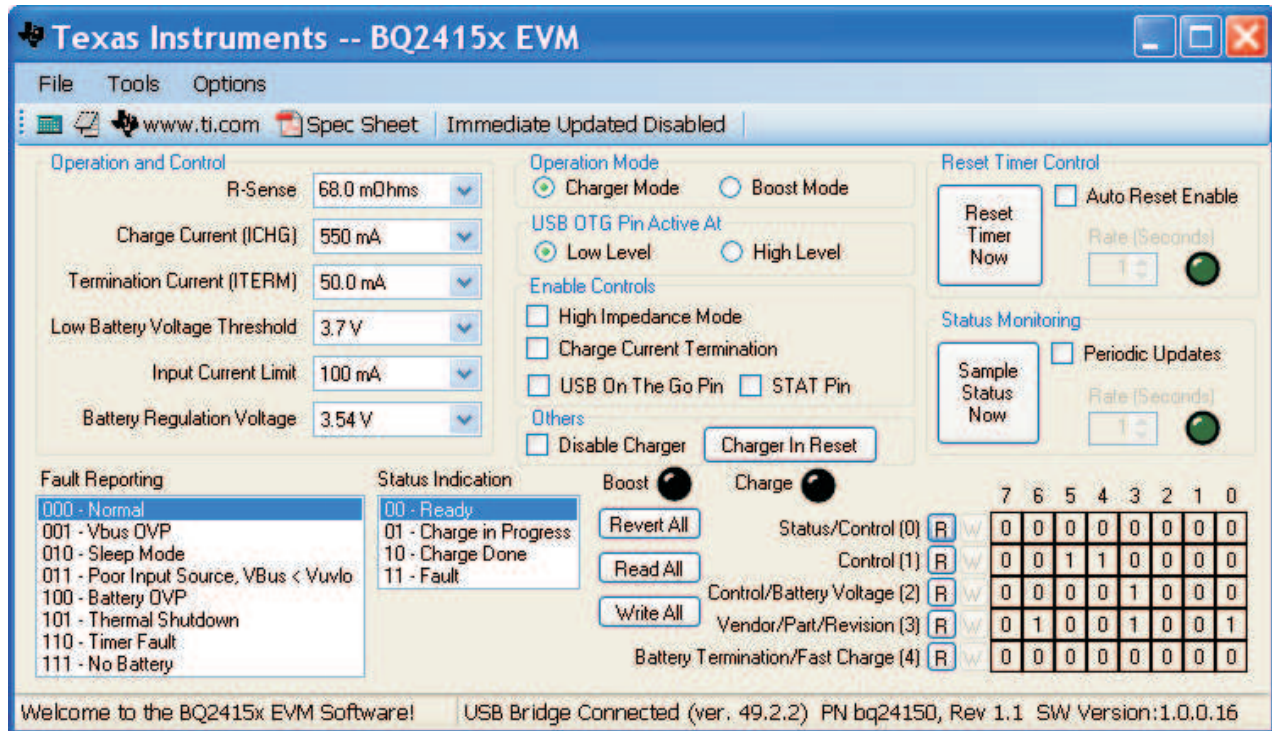


Figure 3. The Main Window of the bq2415x Evaluation Software

2.4 Procedure

2.4.1 Charge Voltage and Current Regulation

1. Make sure the EQUIPMENT SETUP steps are followed. Turn on PS#1.
2. Software setup: Click Immediate Update Disabled button. It changes to Immediate Update Enabled. Check Auto Reset Enable, set Rate to 5 seconds. Check Periodic Updates, set Rate to 1 second. Make sure Operation Mode is Charger Mode. Uncheck Charge Current Termination. Check STAT Pin. Select Battery Regulation Voltage to 4.20V.

Measure → $V(J2(VBAT+, VBAT-)) = 4.2 \pm 100mV$

Observe → D1 is on.

3. Enable Load #2.

Measure → $V(J2(VBAT+, VBAT-)) = 2.5 \pm 100mV$

Measure → $I_{chrg} = 160mA \pm 40mA$

Measure → $I_{in} = 95mA \pm 5mA$

4. Select Charge Current to 1.25A, select Input Current Limit to 500mA.

Measure → $I_{chrg} = 750mA \pm 100mA$

Measure → $I_{in} = 475mA \pm 25mA$

5. Check Disable Charger. Turn off PS#1, turn off Load #2 and disconnect

2.4.2 Boost Function

1. Adjust PS#1 output to 3.7V and disable the output. Connect the PS#1 in series with a current meter (multimeter) to J2 (CSOUT, BAT-). Make sure a voltage meter is connected across J2 (BAT+, BAT-).
2. Set the Load #1 current to $200mA \pm 20mA$ but disable the output. Connect the output of the Load #1 in

series with a current meter (multimeter) to J1 (DC+, DC-). Make sure a voltage meter is connected across J1 (DC+, DC-). The setup is now like [Figure 4](#) for HPA256.

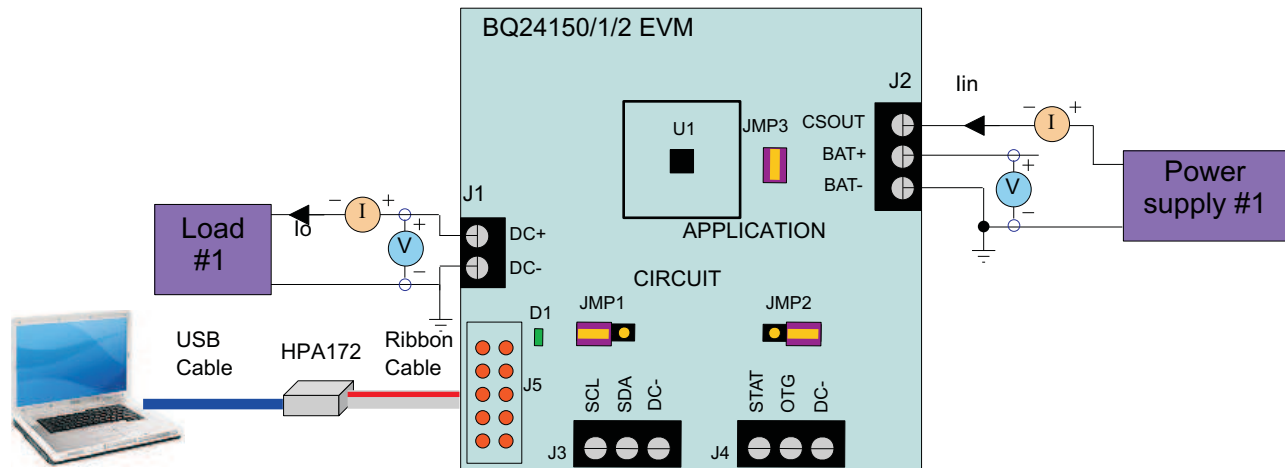


Figure 4. Test setup for HPA256

3. Turn on PS#1 output
4. Software setup: Change Operation Mode to Boost Mode.
Measure → $V(J1(DC+, DC-))=5V \pm 0.2V$
5. Enable Load #1.
Measure → $V(J1(DC+, DC-))=5V \pm 0.2V$
Measure → $I_{in} = 330mA \pm 40mA$
Measure → $I_o = 200mA \pm 20mA$

3 PCB Layout Guideline

1. To obtain optimal performance, the power input capacitors, connected from input to PGND, should be placed as close as possible to the IC.
2. The output inductor should be placed close to the IC and the output capacitor connected between the inductor and PGND of the IC. The intent is to minimize the current path loop area from the SW pin through the LC filter and back to the PGND pin. To prevent high frequency oscillation problems, proper layout to minimize high frequency current path loop is critical.
3. The sense resistor should be adjacent to the junction of the inductor and output capacitor. Route the sense leads connected across the RSNS back to the IC, close to each other (minimize loop area) or on top of each other on adjacent layers (do not route the sense leads through a high-current path).
4. Place all decoupling capacitor close to their respective IC pin and as close as to PGND (do not place components such that routing interrupts power stage currents). All small control signals should be routed away from the high current paths.
5. The PCB should have a ground plane (return) connected directly to the return of all components through vias (two vias per capacitor for power-stage capacitors, two vias for the IC PGND, one via per capacitor for small-signal components). A star ground design approach is typically used to keep circuit block currents isolated (high-power/low-power small-signal) which reduces noise-coupling and ground-bounce issues. A single ground plane for this design gives good results. With this small layout and a single ground plane, there is no ground-bounce issue, and having the components segregated minimizes coupling between signals.
6. The high-current charge paths into VBUS, PMID and from the SW pins must be sized appropriately for the maximum charge current in order to avoid voltage drops in these traces. The PGND pins should be connected to the ground plane to return current through the internal low-side FET.

4 Bill of Materials, Board Layout and Schematics

4.1 Bill of Materials

bq24150-001	bq24151-002	bq24152-003	RefDes	Value	Description	Size	Part Number	MFR
1	1	1	C1	1 μ F	Capacitor, Ceramic, X5R, 16V, \pm 10%	603	GRM188R61C105K	muRata
1	1	1	C2	4.7 μ F	Capacitor, Ceramic, X7R, 16V, \pm 10%	805	GRM21BR71C475K	muRata
2	2	2	C3, C9	10 μ F	Capacitor, Ceramic, X5R, 6.3V, \pm 20%	603	GRM188R60J106M	muRata
2	2	2	C4, C5	1 μ F	Capacitor, Ceramic, X5R, 10V, \pm 10%	402	GRM155R61A105K	muRata
1	1	1	C6	10nF	Capacitor, Ceramic, X5R, 16V, \pm 10%	402	GRM155R61C103K	muRata
2	2	2	C7, C8	0.1 μ F	Capacitor, Ceramic, X7R, 16V, \pm 10%	402	GRM155R71C104K	muRata
1	1	1	D1	Green	Diode, LED, Green, 2.1-V, 20-mA, 6-mcd	603	LTST-C190GKT	Liteon
1	1	1	D2	BAT54C	Diode, Dual Schottky, 200-mA, 30-V	SOT23	BAT54C	Vishay-Liteon
1	1	1	J1	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 \times 0.25 inch	ED1514	OST
3	3	3	J2-J4	ED1515	Terminal Block, 3-pin, 6-A, 3.5mm	0.41 \times 0.25 inch	ED1515	OST
1	1	1	J5	2510-6002UB	Connector, Male Straight 2x5 pin, 100mil spacing, 4 Wall	0.338 \times 0.788 inch	2510-6002UB	3M
2	2	2	JMP1, JMP2	PTC36SAAN	Header, 3-pin, 100mil spacing, (36-pin strip)	0.100 inch \times 3	PTC36SAAN	Sullins
1	1	1	JMP3	PTC36SAAN	Header, 2-pin, 100mil spacing, (36-pin strip)	0.100 inch \times 2	PTC36SAAN	Sullins
3	3	3		929950-00	Shorting jumpers, 2-pin, 100mil spacing		929950-00	3M/ESD
1	1	1	L1	1.0 μ H	2.5mmx2mm, 1.0 μ H, \pm 30%, 1.5A	0.11x0.09 inch	LQM2HPN1R0MJ0 or MIPS2520D1R0 or MDT2520CN1R0M or CP1008	muRata or FDK or TOKO or Inter-technical
1	1	1	R1	0.068m Ω	Resistor, Chip, 68-m Ω , 125mW, 5%	402	ERJ-2BWJR068X	Panasonic
1	1	1	R2	5.1k Ω	Resistor, Chip, 5.1-k Ω , 1/16-W, 5%	603	Std	Std
1	1	1	R3	100k Ω	Resistor, Chip, 100-k Ω , 1/16-W, 5%	603	Std	Std
1	0	0	U1	BQ24150YFF	IC, Battery Charger for Single-Cell Li-Ion and Li-Polymer Battery	WCSP	BQ24150YFF	TI
0	1	0	U1	BQ24151YFF	IC, Battery Charger for Single-Cell Li-Ion and Li-Polymer Battery	WCSP	BQ24151YFF	TI
0	0	1	U1	BQ24152YFF	IC, Battery Charger for Single-Cell Li-Ion and Li-Polymer Battery	WCSP	BQ24152YFF	TI
1	1	1	—	HPA256	PCB, 2.0 In \times 2.0 In \times 0.031 In		PCB	Any

4.2 Board Layout

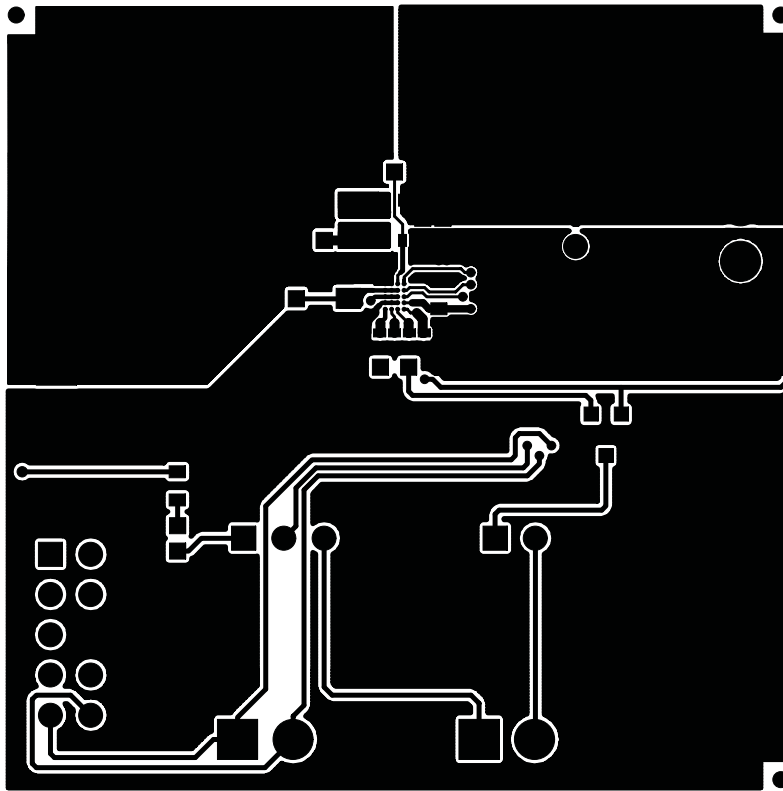


Figure 5. Top Layer

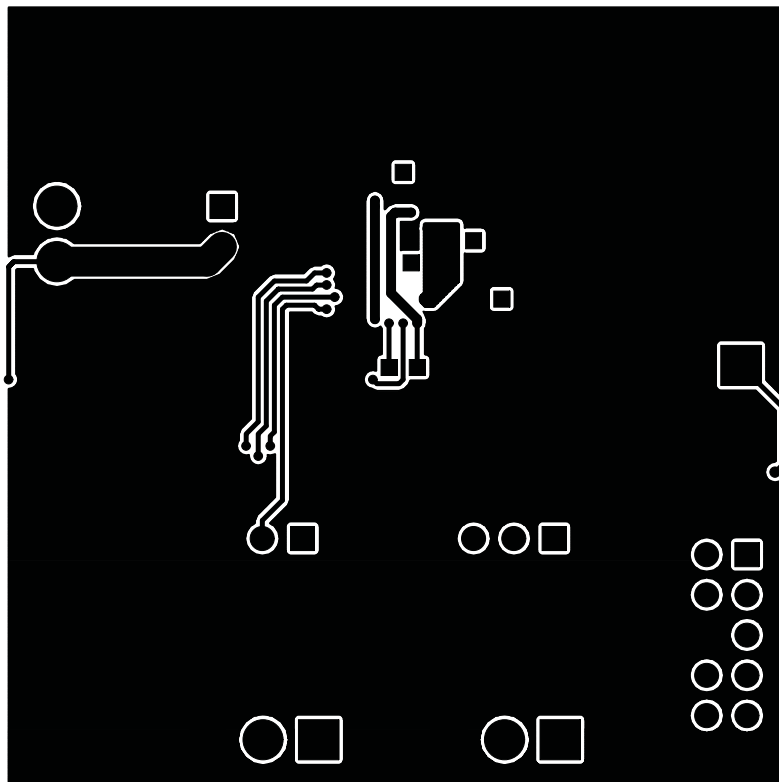


Figure 6. Bottom Layer

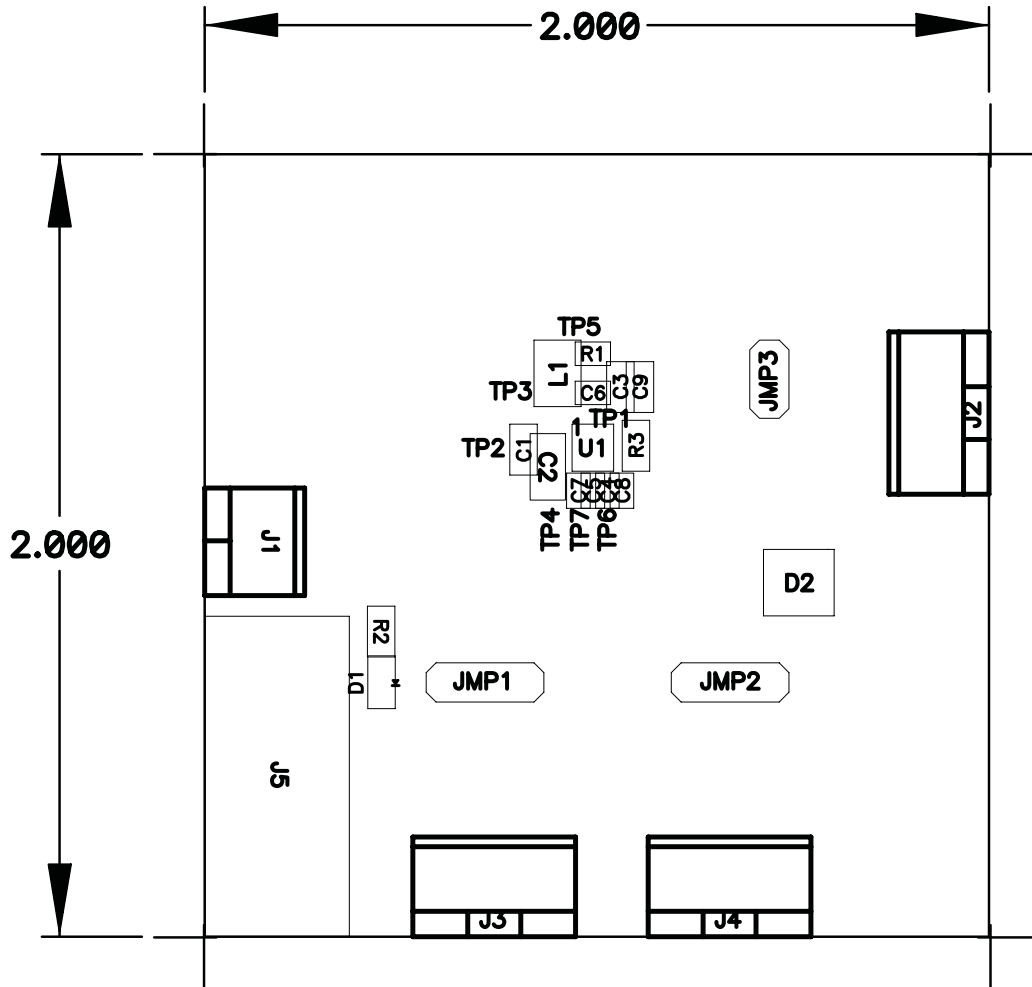


Figure 7. Top Assembly



TEXAS INSTRUMENTS
bq24150/1/2EVM
 HPA256 REV. B

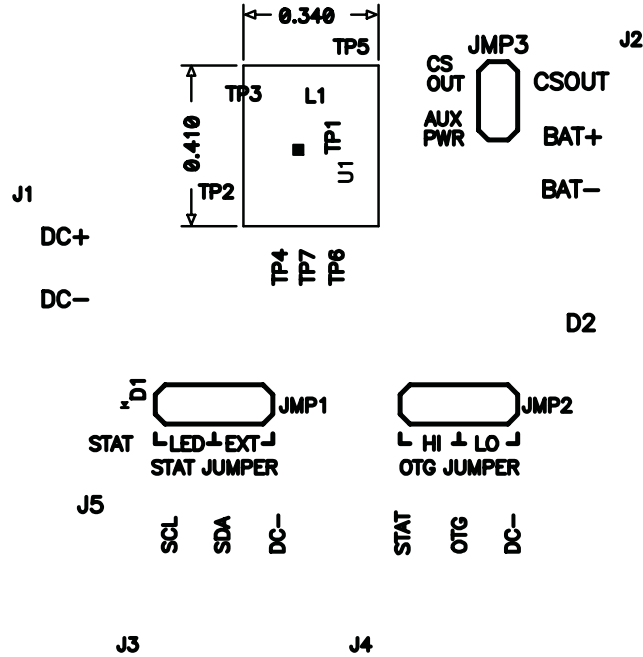
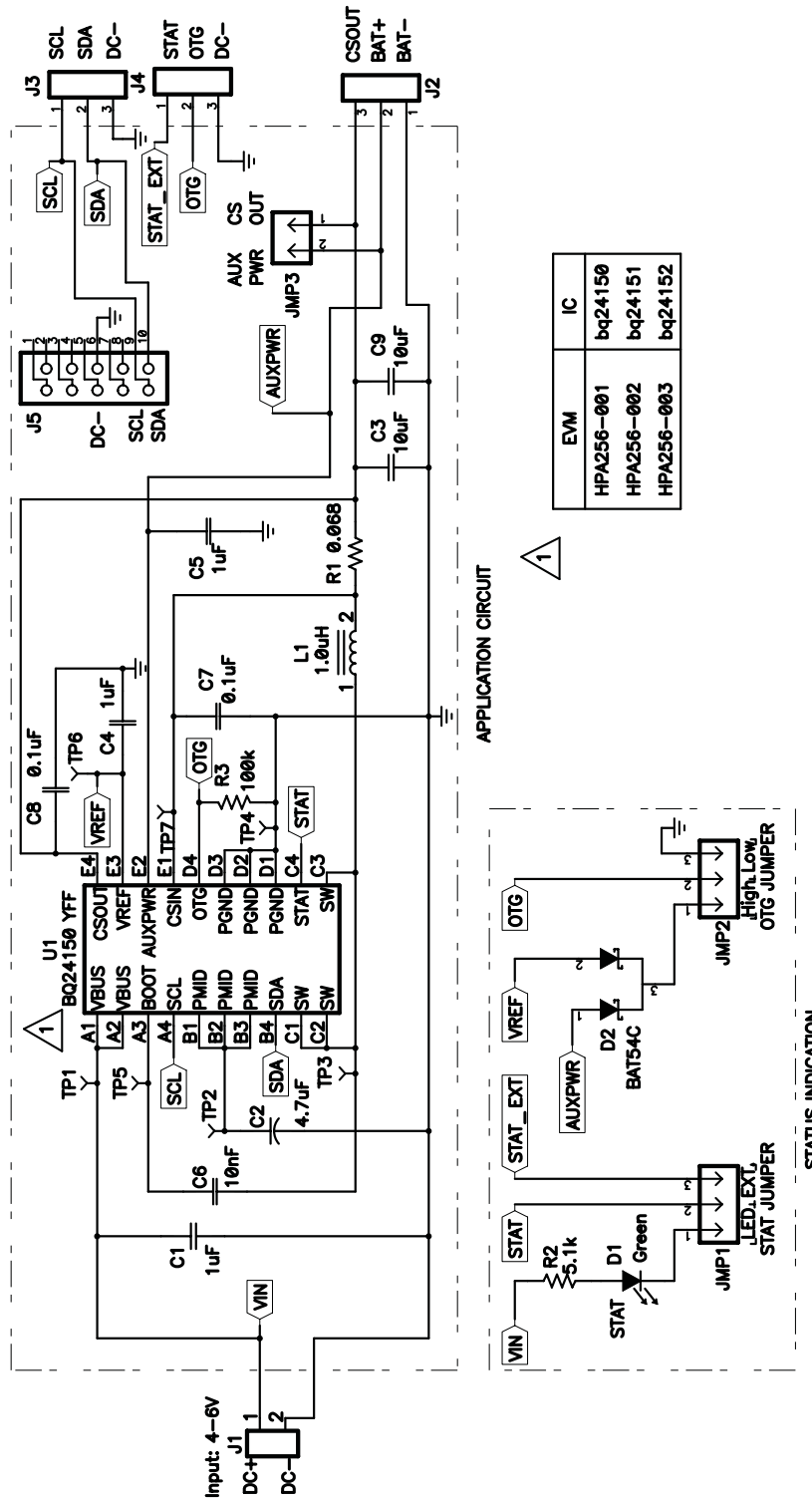


Figure 8. Top Silk

4.3 Schematic



EVM	IC
HPA256-001	bq24150
HPA256-002	bq24151
HPA256-003	bq24152

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It is important to operate this EVM within the input voltage range of 4 V to 6 V and the output voltage range of 0 V to 4.44 V.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 65°C. The EVM is designed to operate properly with certain components above 125°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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